FIG.1

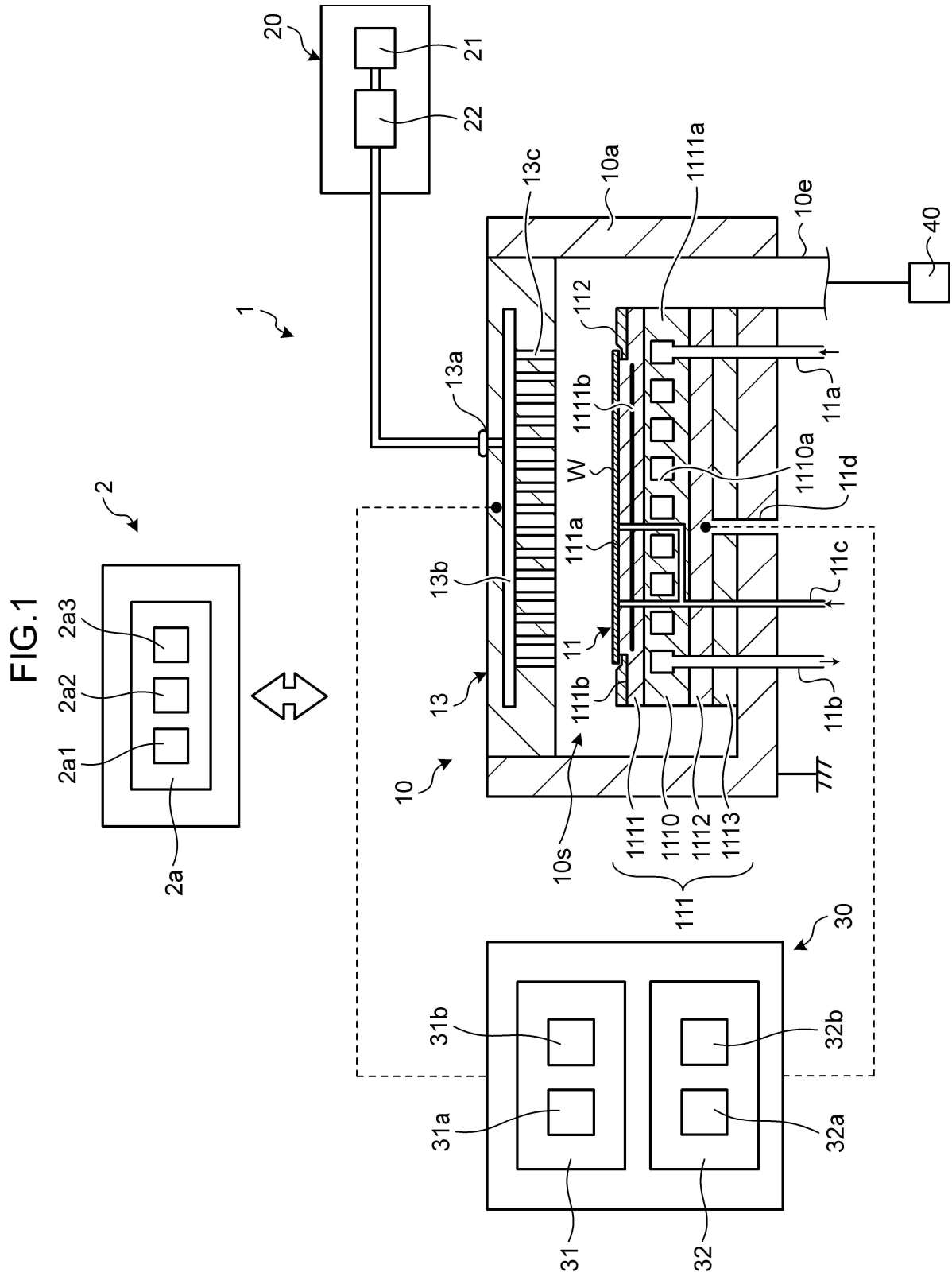

1
2
2a
2a1
2a2
2a3
10
11
111
1110
1111
1112
1113
10s
10a
10e
11a
11b
11c
11d
111a
111b
1111a
1111b
1110a
112
W
13
13a
13b
13c
20
21
22
30
31
31a
31b
32
32a
32b
40

FIG.2

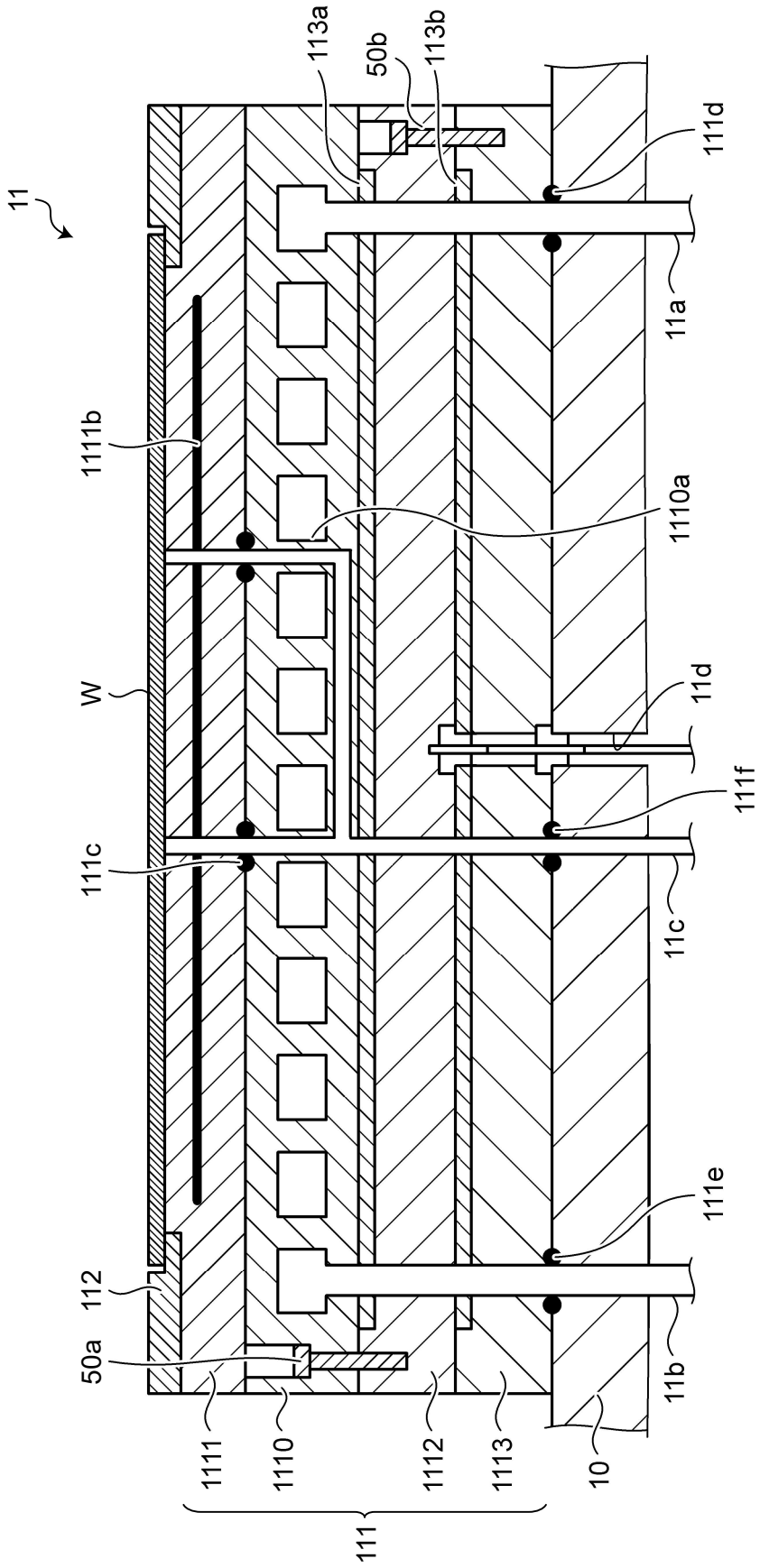

11
113a
50b
113b
111d
11a
1111b
1110a
W
11d
111f
111c
11c
111e
112
50a
11b
1111
1110
1112
1113
10
111

FIG.3

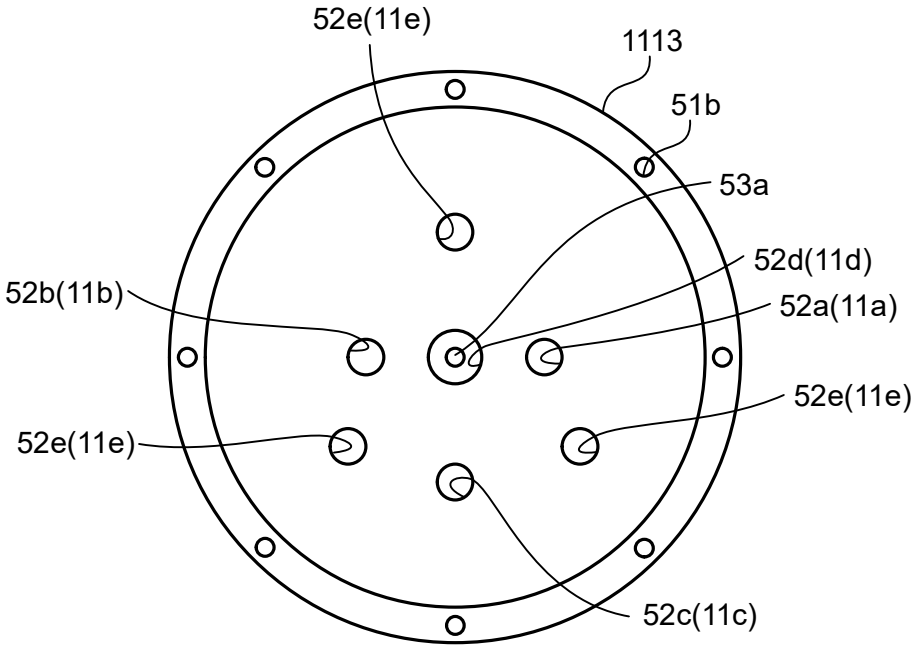

52e(11e)
1113
51b
53a
52d(11d)
52b(11b)
52a(11a)
52e(11e)
52e(11e)
52c(11c)

FIG.4A

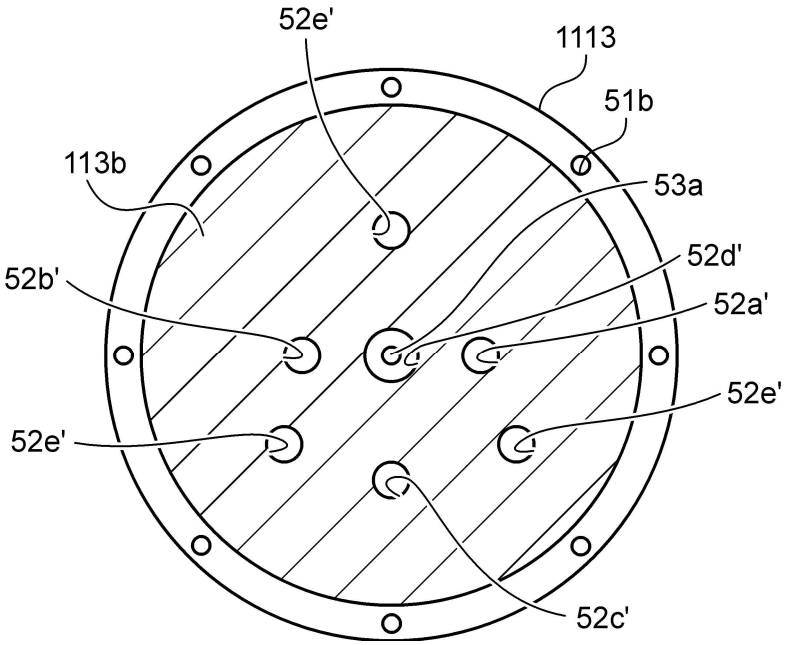


FIG.4B

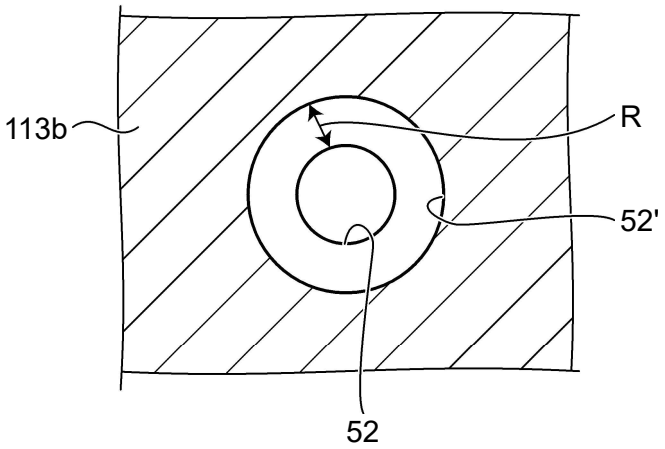


FIG.4C

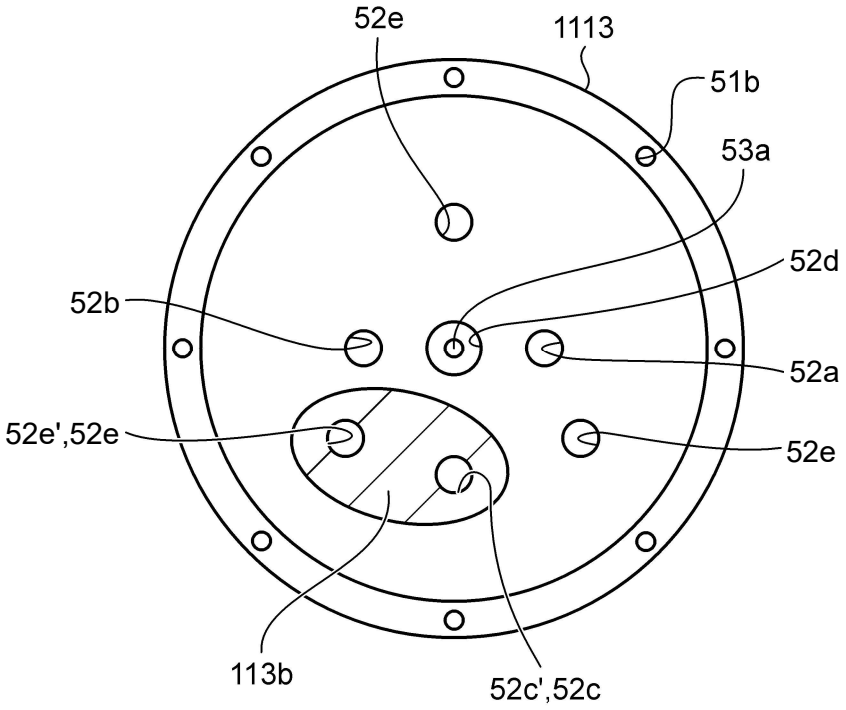


FIG.5

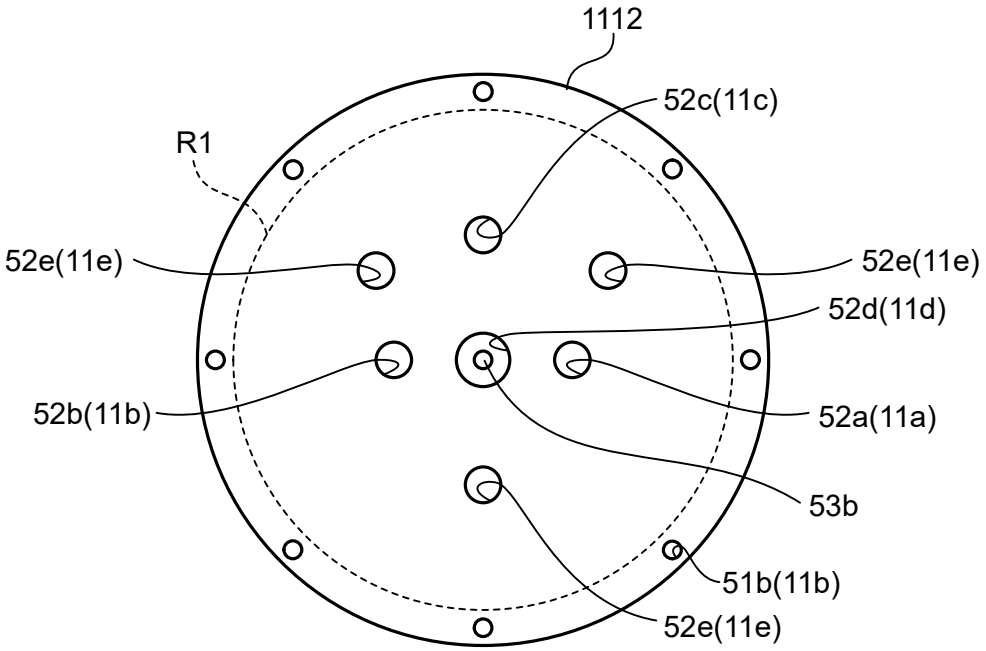

1112
52c(11c)
R1
52e(11e)
52e(11e)
52d(11d)
52b(11b)
52a(11a)
53b
51b(11b)
52e(11e)

FIG.6

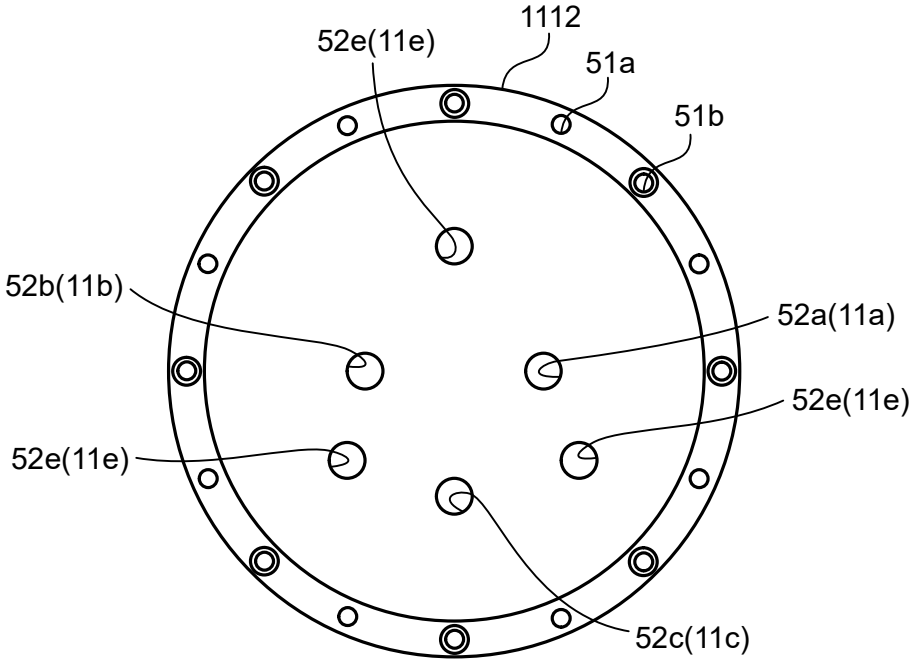

1112
52e(11e)
51a
51b
52b(11b)
52a(11a)
52e(11e)
52e(11e)
52c(11c)

FIG.7

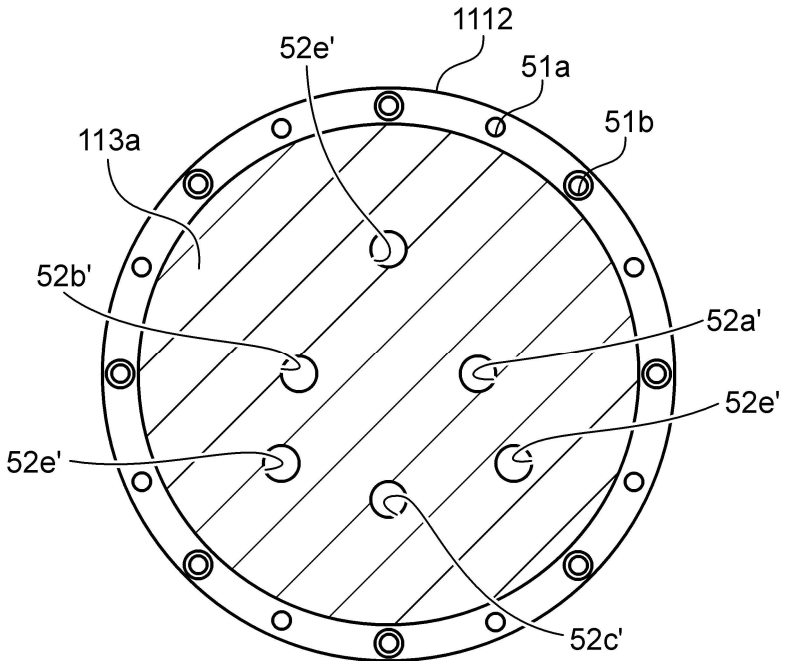

1112
52e'
51a
51b
113a
52b'
52a'
52e'
52e'
52c'

FIG.8

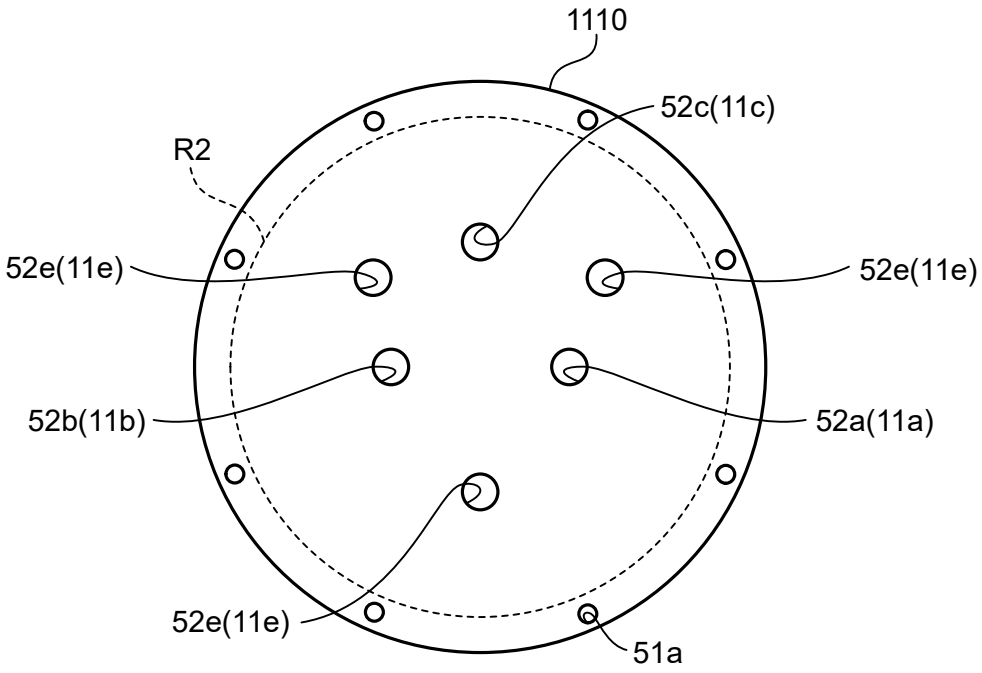

1110
52c(11c)
R2
52e(11e)
52e(11e)
52b(11b)
52a(11a)
52e(11e)
51a

FIG.9

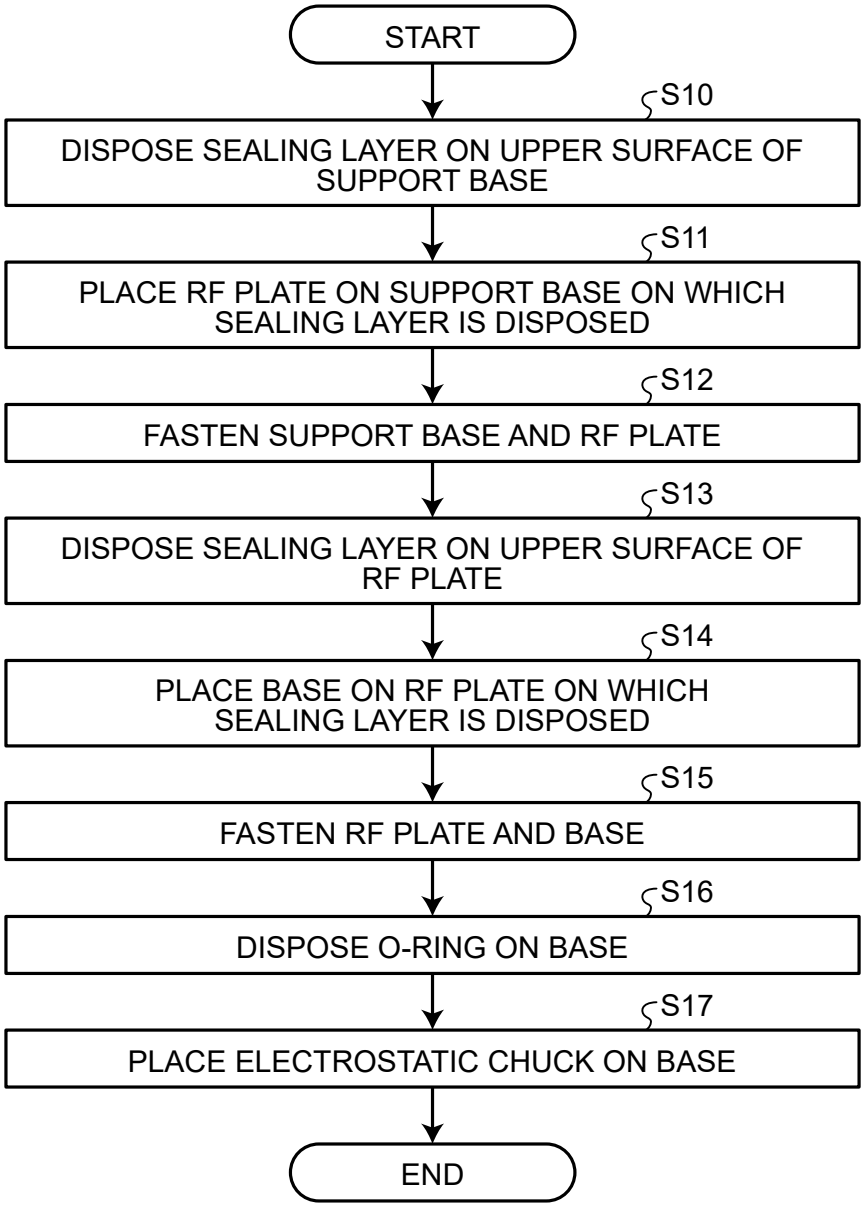

START
S10
DISPOSE SEALING LAYER ON UPPER SURFACE OF SUPPORT BASE
S11
PLACE RF PLATE ON SUPPORT BASE ON WHICH SEALING LAYER IS DISPOSED
S12
FASTEN SUPPORT BASE AND RF PLATE
S13
DISPOSE SEALING LAYER ON UPPER SURFACE OF RF PLATE
S14
PLACE BASE ON RF PLATE ON WHICH SEALING LAYER IS DISPOSED
S15
FASTEN RF PLATE AND BASE
S16
DISPOSE O-RING ON BASE
S17
PLACE ELECTROSTATIC CHUCK ON BASE
END

FIG.10

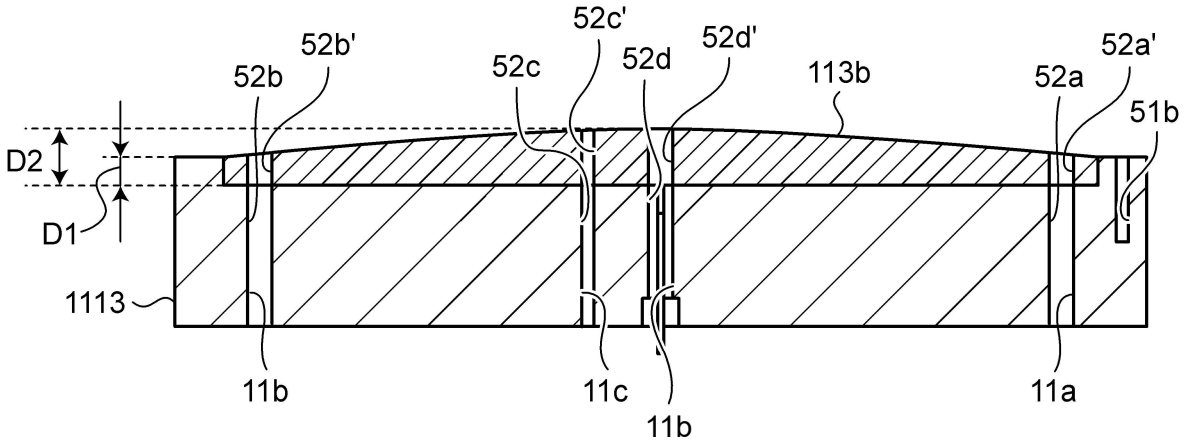

52c'
52b'
52d'
52a'
52b
52c
52d
113b
52a
51b
D2
D1
1113
11b
11c
11b
11a

FIG.11

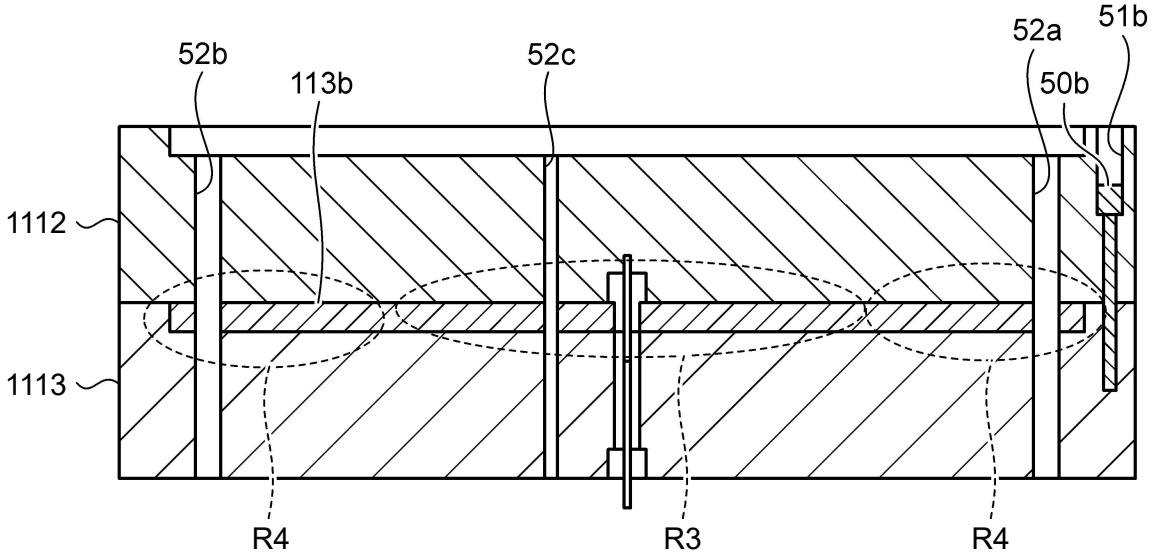

52b
113b
52c
52a
51b
50b
1112
1113
R4
R3
R4

FIG.12

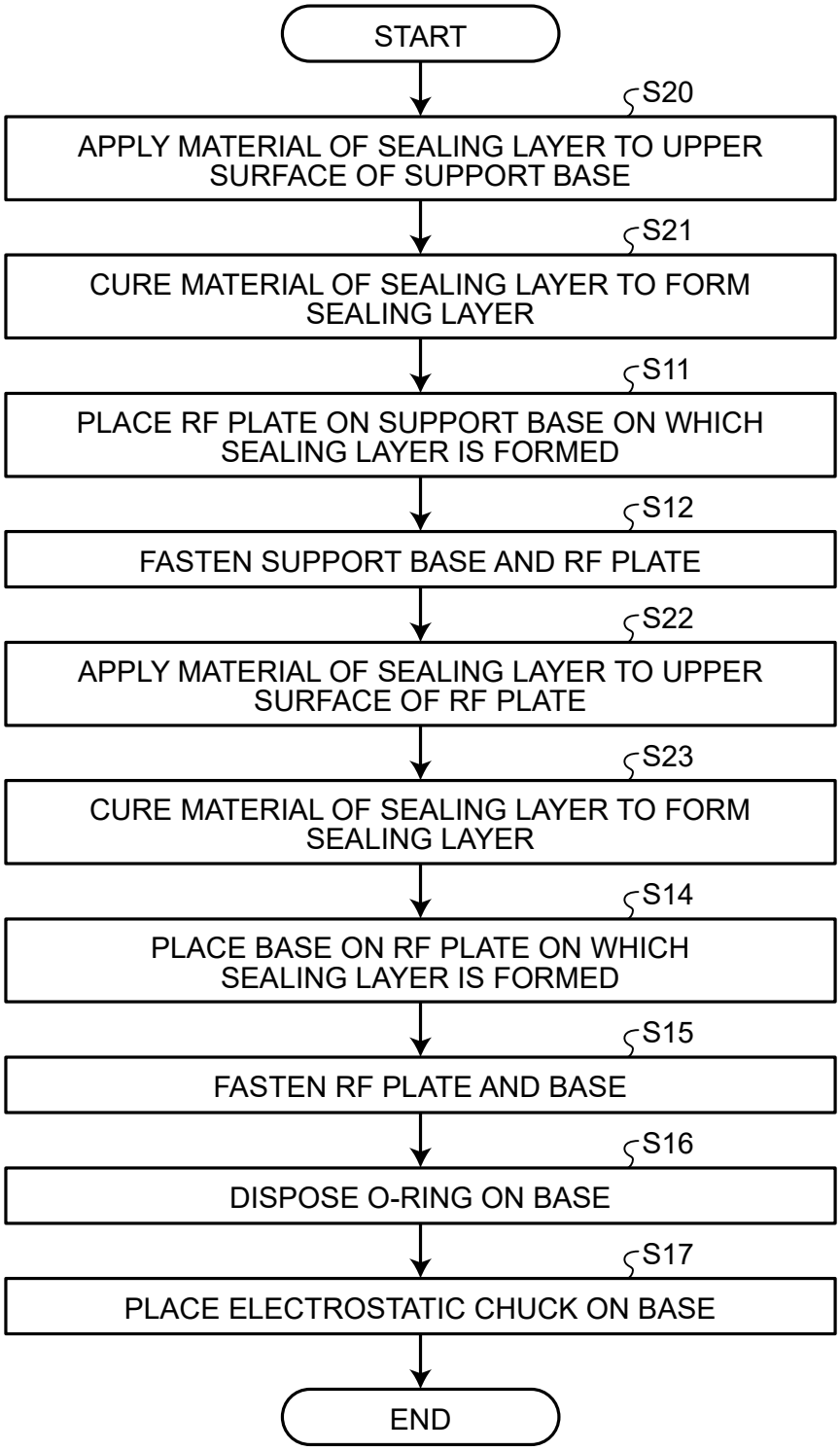
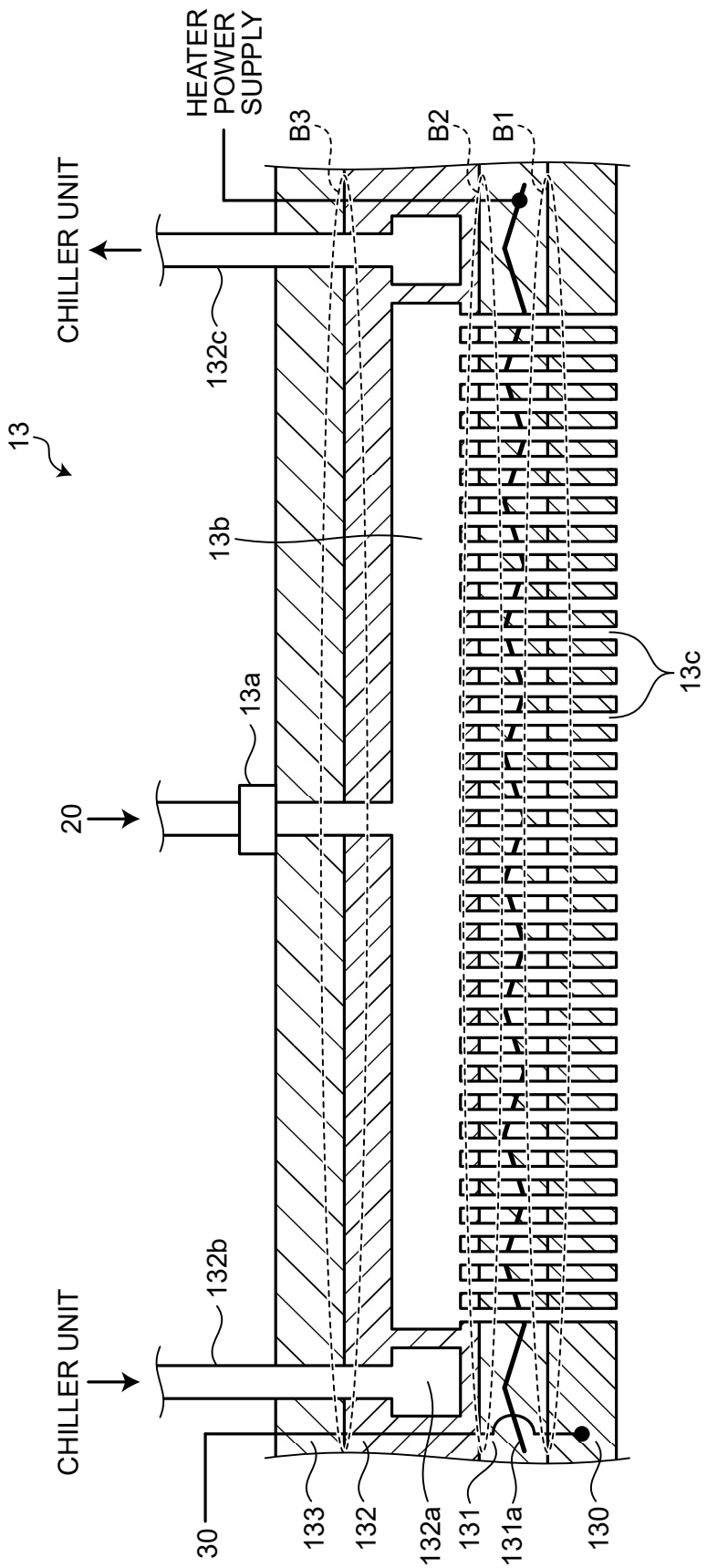

START
S20
APPLY MATERIAL OF SEALING LAYER TO UPPER SURFACE OF SUPPORT BASE
S21
CURE MATERIAL OF SEALING LAYER TO FORM SEALING LAYER
S11
PLACE RF PLATE ON SUPPORT BASE ON WHICH SEALING LAYER IS FORMED
S12
FASTEN SUPPORT BASE AND RF PLATE
S22
APPLY MATERIAL OF SEALING LAYER TO UPPER SURFACE OF RF PLATE
S23
CURE MATERIAL OF SEALING LAYER TO FORM SEALING LAYER
S14
PLACE BASE ON RF PLATE ON WHICH SEALING LAYER IS FORMED
S15
FASTEN RF PLATE AND BASE
S16
DISPOSE O-RING ON BASE
S17
PLACE ELECTROSTATIC CHUCK ON BASE
END

FIG.13


HEATER POWER SUPPLY
B3
B2
B1
CHILLER UNIT
132c
13
13b
13a
13c
20
CHILLER UNIT
132b
30
133
132
132a
131
131a
130